L Number	Hits		DB	Time stamp
1	1779	(438/612).ccls. and @ad<=20020109	USPAT;	2003/01/23 08:47
1			US-PGPUB; EPO; JPO;	
	•		DERWENT;	
			IBM_TDB	
2	1	some and here small collines seems	USPĀT;	2003/01/23 08:46
		'buffer'	US-PGPUB;	
1		1	EPO; JPO; DERWENT;	i I
	ļ		IBM TDB	
3	11	'bond' and 'pad' with copper with 'Al' and	USPAT;	2003/01/23 08:54
	1	'buffer'	US-PGPUB;	
	1		EPO; JPO;	
:			DERWENT;	
4	284	; (438/48).ccls. and @ad<=20020109	IBM_TDB USPAT;	2003/01/23 08:47
		(1307 10).ccis. and eda 20020103	US-PGPUB;	1
			EPO; JPO;	1
	 		DERWENT;	
7	1700	(420/614)	IBM_TDB	
'	1722	(438/614).ccls. and @ad<=20020109	USPAT;	2003/01/23 10:35
1	i	1	US-PGPUB; EPO; JPO;	
1	I		DERWENT;	
i		i	IBM_TDB	
8	573	(257/459).ccls. and @ad<=20020109	USPĀT;	2003/01/23 08:49
			US-PGPUB;	
1	1		EPO; JPO; DERWENT;	
			IBM TDB	
9	1222	(257/784).ccls. and @ad<=20020109	USPAT;	2003/01/23 10:37
:	l		US-PGPUB;	i
			EPO; JPO;	
1			DERWENT; IBM TDB	1
10	1209	(257/786).ccls. and @ad<=20020109	USPAT;	2003/01/23 08:51
1			US-PGPUB;	2000,01,20 00.01
			EPO; JPO;	
			DERWENT;	
11	735	(257/781-782).ccls. and @ad<=20020109	IBM_TDB USPAT;	2003/01/23 08:52
	, , , , ,	(237/701 702/.0013. and (adv-2002010)	US-PGPUB;	2003/01/23 06:32
			EPO; JPO;	
			DERWENT;	
12	1392	(257/774).ccls. and @ad<=20020109	IBM TDB	. 00002/01/02 11 44
12	1392	(237/774).CCIS. and @ad<=20020109	USPAT; US-PGPUB;	2003/01/23 11:44
			EPO; JPO;	
			DERWENT;	
1 2	_		IBM_TDB	
13	1	'bond pad' with 'copper' with 'Al' and 'buffer'	USPAT;	2003/01/23 08:55
		Parter	US-PGPUB; EPO; JPO;	!
!			DERWENT;	I
			IBM_TDB	i
14	1	'bonding pad' with 'copper' with 'Al' and	USPĀT;	2003/01/23 08:56
		'buffer'	US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
15	122	'bonding pad' with 'Cu' with 'Al'	USPAT;	2003/01/23 09:05
			US-PGPUB;	:
			EPO; JPO;	1
			DERWENT; IBM TDB	, 1
16	117	@ad<=20020109 and 'bonding pad' with 'Cu'	USPAT;	2003/01/23 09:01
		with 'Al'	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	F
L			IBM_TDB	

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C:\APPS\east\workspaces\Solder Ball Bonding Pad 438_612 257_737\100433709 bonding pad 438_612.wsp

29	6	@ad<=20020109 and cu adj 'bonding pad' with 'Al'	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/01/23 09:03
30	117	@ad<=20020109 and 'bonding pad' with 'Cu' with 'Al'	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/01/23 09:05
33 34 35 36 49	1 1 1 246		IBM_TDB USPAT USPAT USPAT USPAT USPAT; US-PGPUB;	2003/01/23 09:57 2003/01/23 09:57 2003/01/23 09:57 2003/01/23 09:58 2003/01/23 10:02
50	231	(257/784).ccls. and @ad<=20020109 and 'Copper' and 'aluminum'	EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/01/23 10:38
_ -	2054	(438/612).ccls. or (438/597).ccls. and @ad<=20020109	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/01/23 08:44
	337	((438/612).ccls. or (438/597).ccls. and @ad<=20020109) and copper and aluminum	DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/08/21 11:04
-	74	((438/612).ccls. or (438/597).ccls. and @ad<=20020109) and 'bonding pad' with 'integrated circuit'	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/01/23 10:01
-	1	((438/612).ccls. or (438/597).ccls. and @ad<=20020109) and Cu adj bonding adj pad with 'integrated circuit'	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/08/21 11:13
-	6	((438/612).ccls. or (438/597).ccls. and @ad<=20020109) and Copper adj bonding adj pad	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/08/21 11:14
-	1143	<pre>@ad<=20020109 and cu adj 'bonding pad' with 'IMD' or 'intermetal dielectric'</pre>	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/08/21 11:45
	0	<pre>@ad<=20020109 and cu adj 'bonding pad' with 'IMD'</pre>	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	i ! 2002/08/21 11:27
-	0	<pre>@ad<=20020109 and cu adj 'bonding pad' with 'intermetal dielectric'</pre>	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/08/21 11:27
_	6	<pre>@ad<=20020109 and cu adj 'bonding pad' with 'Al'</pre>	IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/01/23 09:03

Search History 1/23/03 12:49:43 PM Page 2 C:\APPS\east\workspaces\Solder Ball Bonding Pad 438_612 257_737\100433709 bonding pad 438_612.wsp

· <u>·</u> ·] 3	[@ad<=20020109 and cu adj 'bonding pad' and ''IMD'	USPAT; US-PGPUB; EPO; JPO;	2002/08/21	11:43
- -	1		DERWENT; IBM_TDB USPAT USPAT	2002/08/21 2002/08/21	11:40
-	1	"5288006".PN. "5376235".PN. "5384284".PN. "5436412".PN.	USPAT USPAT USPAT USPAT	2002/08/21 2002/08/21 2002/08/21 2002/08/21	11:41 11:41
-	0	@ad<=20020109 and copper adj bonding adj pad with 'intermetal dielectric'	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/08/21	11:45
-	4	@ad<=20020109 and copper adj bonding adj pad and 'intermetal dielectric'	IBM_TDB USPAT; US-PGPUB;	2002/08/21	11:46
:	809	(228/180.21).CCLS.	EPO; JPO; DERWENT; IBM_TDB USPAT;	1 2002/08/21	11:48
1	1		US-PGPUB; EPO; JPO; DERWENT; IBM TDB		
- !	93	((228/180.21).CCLS.) and bonding adj pad	USPĀT; US-PGPUB; EPO; JPO;	2002/08/21	11:50
-	9	((228/180.21).CCLS.) and bonding adj pad with copper	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2002/08/21	13:32
-	 8	((228/180.21).CCLS.) and bond adj pad with copper	US-PGPUB; EPO; JPO;	2002/08/21	13:30
-	. 0	((228/180.21).CCLS.) and bond adj pad with copper with 'Al' adj buffer	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/01/23	08:45
-	0	((228/180.21).CCLS.) and bond adj pad with copper with 'Al'	IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2002/08/21	13:31
-	639	@ad<=20010119 and bonding adj pad with copper	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2002/08/21	13:36
-	359	@ad<=20010119 and bonding adj pad with copper and aluminum	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/08/21	13:47
-	30	@ad<=20010119 and copper adj bonding adj pad and aluminum	IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2002/08/21	13:59
-	839	@ad<=20010119 and bonding adj pad and aluminum and buffer	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/08/21	1.4:00

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4120 bonding pad and apparatus	USPAT; 2002/08/21 15:03 US-PGPUB; EPO; JPO;
3573 ((257/459) or (257/676) or (257/786) or (275/670) or (257/672)).CCLS.	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB